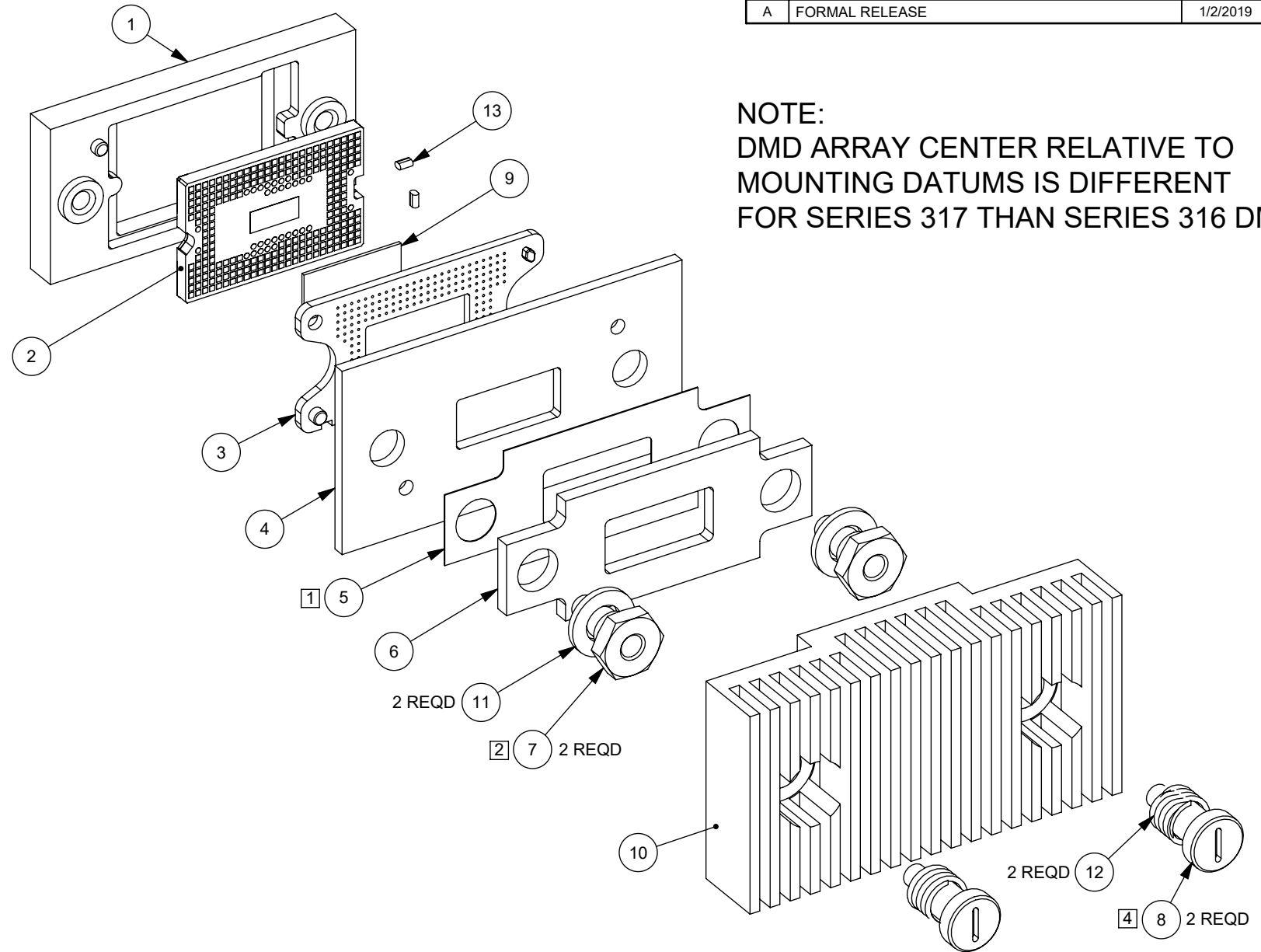
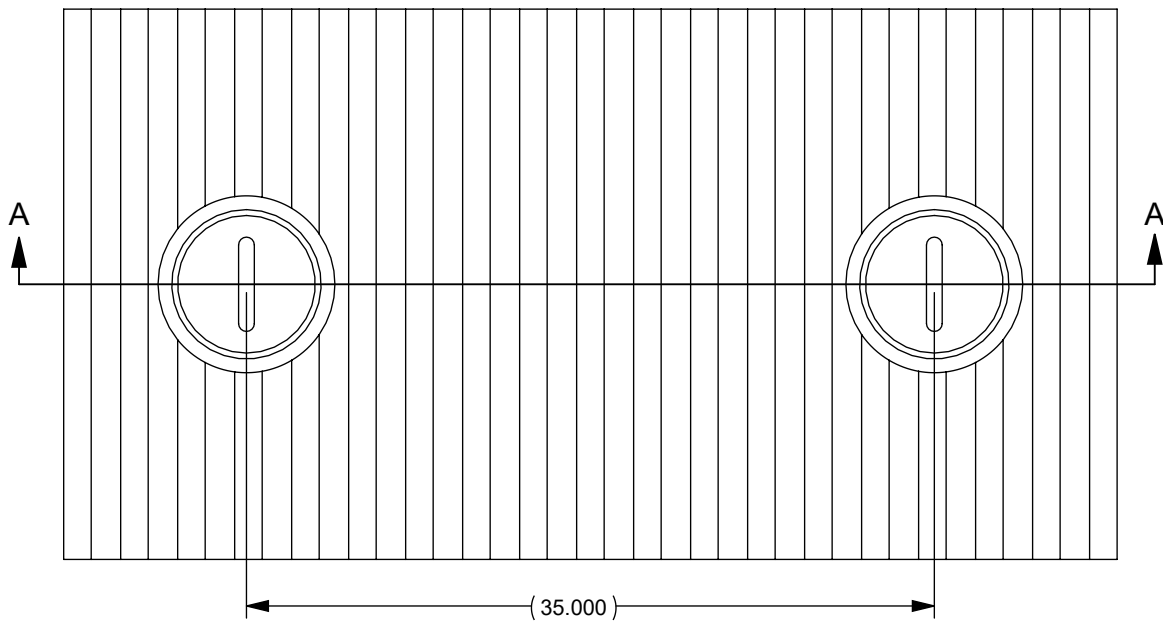
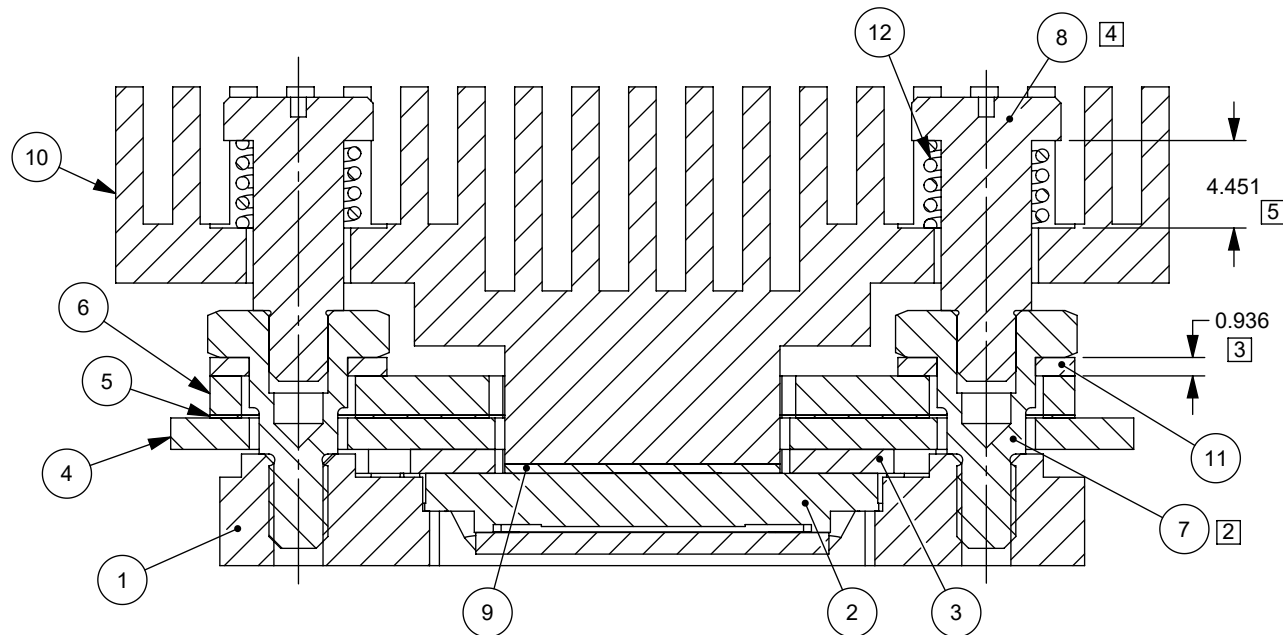


NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 THE INSULATOR (ITEM 5) NEEDS TO BE OF SUFFICIENT THICKNESS TO ISOLATE THE PCB FROM THE METAL CLAMP (ITEM 6), TO KEEP IT FROM CAPACITIVELY COUPLING SIGNALS TOGETHER.
- 2 WHEN TIGHTENING STANDOFFS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOAD FOR THE ELECTRICAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE STANDOFFS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- 3 CRITICAL GAP FOR COMPRESSION WASHER DESIGN TO CONTROL LOADS ON THE DMD ELECTRICAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES. THE RESULTING FORCE APPLIED BY THE COMPRESSION WASHER DEPENDS ON GAP SIZE AND WASHER MATERIAL PROPERTIES.
- 4 WHEN TIGHTENING SCREWS (ITEM 8) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- 5 CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



NOTE:
DMD ARRAY CENTER RELATIVE TO
MOUNTING DATUMS IS DIFFERENT
FOR SERIES 317 THAN SERIES 316 DMD



SECTION A-A

2	13	2512939	SHIM, FOAM ALIGNMENT	
2	12	LEE SPRING LC 026CD 01S	COIL SPRING	
2	11	2515399	WASHER, COMPRESSION	
1	10	2515389	HEAT SINK SERIES 316 AND 317	
1	9	2515390	THERMAL PAD	
2	8	2515396	SCREW, SHOULDER, CONCEPT #1	
2	7	2515252	STANDOFF	
1	6	2515392	CLAMP, SERIES 316 AND 317	
1	5	2515395	PCB INSULATOR, SERIES 316 AND 317	
1	4	2516554	PCB, OUTLINE SERIES 317	
1	3	2515386	INTERPOSER, 250 CONTACT, SERIES 316 AND 317	
1	2		DMD, SERIES 317	
1	1	2515388	INTERFACE, SERIES 316 AND 317	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

Part List

UNLESS OTHERWISE SPECIFIED

- DIMENSIONS ARE IN MILLIMETERS
- TOLERANCES: ANGLES $\pm 1^\circ$
2 PLACE DECIMALS ± 0.25
1 PLACE DECIMALS ± 0.50
- DIMENSIONAL LIMITS APPLY BEFORE PROCESSES
- INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
- REMOVE ALL BURRS AND SHARP EDGES
- PARENTHETICAL INFO FOR REF ONLY

DWN J. McKINLEY	DATE 12/31/2018
Engr	
CQE/QA	
CM	
Apprvd McKINLEY	1/2/2019



ASSEMBLY, SERIES 317 DMD
MOUNTING CONCEPT

SIZE B	DWG NO 2516537	REV A
SCALE 2:1	SHEET 1 OF 2	

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DWG NO
2516537-Assembly

SH
2

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SSZZ031 January 01, 2013

TEXAS
INSTRUMENTS

DWN
J. McKINLEY

DATE
12/31/2018

SIZE
B

DRAWING NO
2516537-Assembly

REV
A

SCALE 2:1

SHEET 2 OF 2

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SW-2012a

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